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(FILE 'HOME' ENTERED AT 13:06:01 ON 21 MAR 2001)

FILE 'REGISTRY' ENTERED AT 13:06:08 ON 21 MAR 2001

L1 443 (1<AG<4 AND 0<CU<2 AND 50<SN)/MAC
L2 14941 (0<NI<.1 OR 0<FE<.1)/MAC
L3 20 L1 AND L2

FILE 'HCA' ENTERED AT 13:07:19 ON 21 MAR 2001

L4 249 L3
L5 9925 (TIN OR SN) AND (IRON OR FE OR NICKEL OR NI) AND (SILVER OR
AG)
L6 24 L4 AND L5
SET NOTICE DISPLAY 1

INDEX 'IFICLS, PATOSEP, PATDPA, INPADOC' ENTERED AT 13:15:32 ON 21 MAR
2001

SEA GB 2319039/PN,APPS

1 FILE INPADOC
L7 QUE GB 2319039/PN,APPS

FILE 'INPADOC' ENTERED AT 13:15:35 ON 21 MAR 2001

L8 1 S L7
SET NOTICE LOGIN DISPLAY

FILE 'HCA' ENTERED AT 13:16:34 ON 21 MAR 2001

SELECT L6 IPC 1 3 5 9 10 12 15 17 23
L9 125805 E1-7
L10 23225 (TIN OR SN) (1A) (ALLOY OR SOLDER? OR BALANC? OR REMAIN? OR
REST?
L11 871 L10 AND (SILVER OR AG) AND (COPPER OR CU) AND (NICKEL OR NI
OR
L12 289 L9 AND L11
L13 143 L12 AND SOLDER?
E ITO TOSHIHIDE/IN,AU
L14 9 E3-4
E HARA SHIRO/IN,AU
L15 30 E3-4
L16 39 L14 OR L15
L17 1 L11 AND L16
L18 892153 LIQUI?
L19 6 L13 AND L18
E JP1177370/PN
E JP01177370/PN
E JP06418981/PN
E JP06471592/PN
E JP04305073/PN
L20 1 E3
E JP02179386/PN
L21 1 E3

AN 134:31904 HCA
 TI Lead-free **solder**
 IN Domi, Shinjiro; Sakaguchi, Koichi; Nakagaki, Shigeki; Suganuma, Katsuaki
 PA Nippon Sheet Glass Co., Ltd., Japan
 SO PCT Int. Appl., 21 pp.
 CODEN: PIXXD2
 DT Patent
 LA Japanese
 FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	WO 2000076717	A1	20001221	WO 2000-JP3631	20000605
	W: CA, CN, KR, US				
	RW: AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE				
	JP 2001058287	A2	20010306	JP 2000-168477	20000606
PRAI	JP 1999-164737		19990611		
AB	The solder contains Sn .gtoreq.90, Ti 0.001-1.0, O 0.1-1.5, Ag 0.1-6.0, Cu 0.001-6.0, Zn 0.001-3.0, Al 0.001-3.0, Bi , Si , and/or Sb .ltoreq.10, Si 0.001-1.0, Fe , Ni , Co , Ga , Ge , and/or P .ltoreq.1.0%, and has a liquidus 200-400.degree..				

RE.CNT 7

RE

- (1) Central Glass Co Ltd; JP 1177370 A 1999
 - (2) Hitachi Ltd; JP 6418981 A 1989
 - (3) Nippon Kogaku K K; JP 6471592 A 1989
 - (6) Tanaka Kikinzoku Kogyo K K; JP 04305073 A 1992 HCA
 - (7) Tokuriki Honten Co Ltd; JP 02179386 A 1990 HCA
- ALL CITATIONS AVAILABLE IN THE RE FORMAT

AN 134:45513 HCA
TI ~~Tin-silver-copper~~-germanium solder alloy
IN Yamashita, Mitsuo; Tada, Shinji; Shiokawa, Kunio
PA Fuji Electric Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 4 pp.
CODEN: JKXXAF

DT Patent
LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	JP 2000343273	A2	20001212	JP 1999-153372	19990601
AB	A Sn solder alloy contains Ag .ltoreq.4, Cu .ltoreq.2, Ge >0.1 and .ltoreq.0.3%, and optionally .ltoreq.1% Ni . The addn. of Ge and Ni prevents Sn oxidn. Pb-free solder is suitable for electronic applications.				

AN 133:285123 HCA
TI Lead-free solder of **tin-silver-bismuth-copper**
alloy
IN Moriyama, Shigeo; Moribayashi, Toshiyuki; Takenaka, Junichi
PA Nihon Genma Mfg. Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 10 pp.
CODEN: JKXXAF

DT Patent
LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	JP 2000288772	A2	20001017	JP 2000-25388	20000202
PRAI	JP 1999-25342		19990202		

AB The solder of **Sn** alloy contains **Ag** 2.0-5.0, Bi
0.1-1.3, **Cu** 0.01-2.0, and P 0.003-0.006 and/or **Ni**
0.005-0.1%. The alloy has high elongation (.gtoreq.30%) and wettability.

AN 133:154041 HCA
TI Lead-free solder
IN Yamashita, Mitsuo; Tada, Shinji; Shiokawa, Kunio
PA Fuji Electric Co., Ltd., Japan
SO Ger. Offen., 8 pp.
CODEN: GWXXBX

DT Patent
LA German

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	DE 10003665	A1	20000803	DE 2000-10003665	20000128
	JP 2000280090	A2	20001010	JP 2000-805	20000106
PRAI	JP 1999-22403		19990129		

AB The Pb-free solder contains Bi .ltoreq.21, **Ag** .ltoreq.4, **Cu** .ltoreq.2, **Ni** .ltoreq.0.2 and/or Ge .ltoreq.0.1%, and **Sn** balance. Wettability and heat resistance of the solder is higher than that of conventional **Sn**-Bi solders. M.p. of the solder is below 221.degree. (the eutectic point of the **Sn**-**Ag** alloy).